

NEXCOM International Co., Ltd.

Network and Communication Solutions Network Security Appliance DNA 1170 Series

User Manual



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PREFACE

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Disclaimer

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Acknowledgements

DNA 1170 series is a trademark of NEXCOM International Co., Ltd. All other product names mentioned herein are registered trademarks of their respective owners.

Regulatory Compliance Statements

This section provides the FCC compliance statement for Class B devices and describes how to keep the system CE compliant.

Declaration of Conformity

FCC

This equipment has been tested and verified to comply with the limits for a Class B digital device, pursuant to Part 15 of FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area (domestic environment) is likely to cause harmful interference, in which case the user will be required to correct the interference (take adequate measures) at their own expense.

CE

The product(s) described in this manual complies with all applicable European Union (CE) directives if it has a CE marking. For computer systems to remain CE compliant, only CE-compliant parts may be used. Maintaining CE compliance also requires proper cable and cabling techniques.



RoHS Compliance



NEXCOM RoHS Environmental Policy and Status Update

NEXCOM is a global citizen for building the digital infrastructure. We are committed to providing green products and services, which are compliant with

European Union RoHS (Restriction on Use of Hazardous Substance in Electronic Equipment) directive 2011/65/EU, to be your trusted green partner and to protect our environment.

RoHS restricts the use of Lead (Pb) < 0.1% or 1,000ppm, Mercury (Hg) < 0.1% or 1,000ppm, Cadmium (Cd) < 0.01% or 100ppm, Hexavalent Chromium (Cr6+) < 0.1% or 1,000ppm, Polybrominated biphenyls (PBB) < 0.1% or 1,000ppm, and Polybrominated diphenyl Ethers (PBDE) < 0.1% or 1,000ppm.

In order to meet the RoHS compliant directives, NEXCOM has established an engineering and manufacturing task force in to implement the introduction of green products. The task force will ensure that we follow the standard NEXCOM development procedure and that all the new RoHS components and new manufacturing processes maintain the highest industry quality levels for which NEXCOM are renowned.

The model selection criteria will be based on market demand. Vendors and suppliers will ensure that all designed components will be RoHS compliant.

How to recognize NEXCOM RoHS Products?

For existing products where there are non-RoHS and RoHS versions, the suffix "(LF)" will be added to the compliant product name.

All new product models launched after January 2013 will be RoHS compliant. They will use the usual NEXCOM naming convention.





Warranty and RMA

NEXCOM Warranty Period

NEXCOM manufactures products that are new or equivalent to new in accordance with industry standard. NEXCOM warrants that products will be free from defect in material and workmanship for 2 years, beginning on the date of invoice by NEXCOM. HCP series products (Blade Server) which are manufactured by NEXCOM are covered by a three year warranty period.

NEXCOM Return Merchandise Authorization (RMA)

- Customers shall enclose the "NEXCOM RMA Service Form" with the returned packages.
- Customers must collect all the information about the problems encountered and note anything abnormal or, print out any on-screen messages, and describe the problems on the "NEXCOM RMA Service Form" for the RMA number apply process.
- Customers can send back the faulty products with or without accessories (manuals, cable, etc.) and any components from the card, such as CPU and RAM. If the components were suspected as part of the problems, please note clearly which components are included. Otherwise, NEXCOM is not responsible for the devices/parts.
- Customers are responsible for the safe packaging of defective products, making sure it is durable enough to be resistant against further damage and deterioration during transportation. In case of damages occurred during transportation, the repair is treated as "Out of Warranty."
- Any products returned by NEXCOM to other locations besides the customers' site will bear an extra charge and will be billed to the customer.

Repair Service Charges for Out-of-Warranty Products

NEXCOM will charge for out-of-warranty products in two categories, one is basic diagnostic fee and another is component (product) fee.

Repair Service Charges for Out-of-Warranty Products

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System Level

- Component fee: NEXCOM will only charge for main components such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistor, capacitor.
- Items will be replaced with NEXCOM products if the original one cannot be repaired. Ex: motherboard, power supply, etc.
- Replace with 3rd party products if needed.
- If RMA goods can not be repaired, NEXCOM will return it to the customer without any charge.

Board Level

- Component fee: NEXCOM will only charge for main components, such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistors, capacitors.
- If RMA goods can not be repaired, NEXCOM will return it to the customer without any charge.





Warnings

Read and adhere to all warnings, cautions, and notices in this guide and the documentation supplied with the chassis, power supply, and accessory modules. If the instructions for the chassis and power supply are inconsistent with these instructions or the instructions for accessory modules, contact the supplier to find out how you can ensure that your computer meets safety and regulatory requirements.

Cautions

Electrostatic discharge (ESD) can damage system components. Do the described procedures only at an ESD workstation. If no such station is available, you can provide some ESD protection by wearing an antistatic wrist strap and attaching it to a metal part of the computer chassis.



Safety Information

Before installing and using the device, note the following precautions:

- Read all instructions carefully.
- Do not place the unit on an unstable surface, cart, or stand.
- Follow all warnings and cautions in this manual.
- When replacing parts, ensure that your service technician uses parts specified by the manufacturer.
- Avoid using the system near water, in direct sunlight, or near a heating device.
- The load of the system unit does not solely rely for support from the rackmounts located on the sides. Firm support from the bottom is highly necessary in order to provide balance stability.
- The computer is provided with a battery-powered real-time clock circuit. There is a danger of explosion if battery is incorrectly replaced. Replace only with the same or equivalent type recommended by the manufacturer. Discard used batteries according to the manufacturer's instructions.

Installation Recommendations

Ensure you have a stable, clean working environment. Dust and dirt can get into components and cause a malfunction. Use containers to keep small components separated.

Adequate lighting and proper tools can prevent you from accidentally damaging the internal components. Most of the procedures that follow require only a few simple tools, including the following:

- A Philips screwdriver
- A flat-tipped screwdriver
- A grounding strap
- An anti-static pad

Using your fingers can disconnect most of the connections. It is recommended that you do not use needle-nose pliers to disconnect connections as these can damage the soft metal or plastic parts of the connectors.





Safety Precautions

- 1. Read these safety instructions carefully.
- 2. Keep this User Manual for later reference.
- 3. Disconnect this equipment from any AC outlet before cleaning. Use a damp cloth. Do not use liquid or spray detergents for cleaning.
- 4. For plug-in equipment, the power outlet socket must be located near the equipment and must be easily accessible.
- 5. Keep this equipment away from humidity.
- 6. Put this equipment on a stable surface during installation. Dropping it or letting it fall may cause damage.
- 7. The openings on the enclosure are for air convection to protect the equipment from overheating. DO NOT COVER THE OPENINGS.
- 8. Make sure the voltage of the power source is correct before connecting the equipment to the power outlet.
- 9. Place the power cord in a way so that people will not step on it. Do not place anything on top of the power cord. Use a power cord that has been approved for use with the product and that it matches the voltage and current marked on the product's electrical range label. The voltage and current rating of the cord must be greater than the voltage and current rating marked on the product.
- 10. All cautions and warnings on the equipment should be noted.

- 11. If the equipment is not used for a long time, disconnect it from the power source to avoid damage by transient overvoltage.
- 12. Never pour any liquid into an opening. This may cause fire or electrical shock
- 13. Never open the equipment. For safety reasons, the equipment should be opened only by qualified service personnel.
- 14. If one of the following situations arises, get the equipment checked by service personnel:
 - a. The power cord or plug is damaged.
 - b. Liquid has penetrated into the equipment.
 - c. The equipment has been exposed to moisture.
 - d. The equipment does not work well, or you cannot get it to work according to the user's manual.
 - e. The equipment has been dropped and damaged.
 - f. The equipment has obvious signs of breakage.
- 15. Do not place heavy objects on the equipment.
- 16. The unit uses a three-wire ground cable which is equipped with a third pin to ground the unit and prevent electric shock. Do not defeat the purpose of this pin. If your outlet does not support this kind of plug, contact your electrician to replace your obsolete outlet.
- 17. CAUTION: DANGER OF EXPLOSION IF BATTERY IS INCORRECTLY REPLACED. REPLACE ONLY WITH THE SAME OR EQUIVALENT TYPE RECOMMENDED BY THE MANUFACTURER. DISCARD USED BATTERIES ACCORDING TO THE MANUFACTURER'S INSTRUCTIONS.





Technical Support and Assistance

- For the most updated information of NEXCOM products, visit NEXCOM's website at www.nexcom.com.
- 2. For technical issues that require contacting our technical support team or sales representative, please have the following information ready before calling:
 - Product name and serial number
 - Detailed information of the peripheral devices
 - Detailed information of the installed software (operating system, version, application software, etc.)
 - A complete description of the problem
 - The exact wordings of the error messages

Warning!

- 1. Handling the unit: carry the unit with both hands and handle it with care.
- 2. Maintenance: to keep the unit clean, use only approved cleaning products or clean with a dry cloth.

Conventions Used in this Manual



Warning:

Information about certain situations, which if not observed, can cause personal injury. This will prevent injury to yourself when performing a task.



Caution:

Information to avoid damaging components or losing data.



Note:

Provides additional information to complete a task easily.



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Package Contents

Before continuing, verify that the DNA 1170 package that you received is complete. Your package should have all the items listed in the following table.

Item	Part Number	Name	Description	Qty
1	5044440031X00	RUBBER FOOT KANG YANG:RF20-5-4P	19.8x18x5.0mm	4
2	60110A0342X00	ACCESSORY BOX FOR DNA1170 SERIES VER:A FULPAK	250x176x60mm E FLUTE 5KG	1
3	6012200053X00	PE ZIPPER BAG #3 炎洲:印刷由任袋3號	100x70mm,W/China RoHS SYMBOL	1
4	6023309081X00	CABLE EDI:232091081804-RS	COM PORT. DB9 FEMALE TO RJ45 8P8C L:1800mm	1



Ordering Information

The following below provides ordering information for DNA 1170.

Barebone

DNA 1170 (by request)

Intel Atom® processor C5315, BGA type 4 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports

DNA 1170A (P/N: 10L00117001X0)

Intel Atom® processor C5325, BGA type 8 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports

DNA 1170W (by request)

Intel Atom® processor C5325, BGA type 8 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports, 1 x mini-PCle slot for Wi-Fi module & 1 x M.2 3042 Key B for 5G/LTE module



CHAPTER 1: PRODUCT INTRODUCTION

Overview





Key Features

- Intel Atom® C5315/C5325 processor
- 2 x DDR4 SODIMM, up to 16GB
- 8 x 1GbE RJ45 ports
- 4 x SFP+ ports

- 2 x 65W AC power adapters
- Supports Wi-Fi 6E (optional)
- Supports LTE/5G (optional)
- 4 x 1GbE RJ45 ports with 2 x bypass pairs



Hardware Specifications

Main Board

- Intel Atom® C5000 processor w/ QAT
 - Intel Atom® processor C5315, BGA type, 4 cores/2.4 GHz for DNA 1170
 - Intel Atom® processor C5325, BGA type, 8 cores/2.4 GHz for DNA 1170A
 - Intel Atom® processor C5325, BGA type, 8 cores/2.4 GHz for DNA 1170W

Main Memory

2GB2 x DDR4 2933 SODIMM, up to 16GB

Storage

- 1 x M.2 Key M 2242 for SATA 3.0
- 2 x 2.5" SSD SATA 3.0 (DNA 1170W)

Interface External

- Button: power and reset
- LED: status/MGMT/HA/PWR1/PWR2/SSD/LAN
- LED (optional): bypass/5G LTE/Wi-Fi
- 1 x RJ45 console port
- 3 x USB 3.0 connector
- 1 x Nano SIM slot (DNA 1170W)
- 1 x 1G RJ45 management port
- 8 x 1GbE RJ45 ports
 - 4 x 1GbE RJ45 ports with 2 x bypass pairs
- 4 x SFP+ ports
- 1 x Fixed smart fan

- 2 x Power inlets
- 6 x Antenna holes (4 x antennas for 5G LTE, 2 x antennas for Wi-Fi 6E) (DNA 1170W)

Interface Internal

- 1 x mini-PCle slot for Wi-Fi module (DNA 1170W)
- 1 x M.2 3042 Key B for 5G/LTE module (DNA 1170W)
- 1 x TPM header

Power

2 x 65W 19V AC power adapters

Dimension and Weight

- Chassis dimension (mm): 340 x 250 x 44 (W x D x H)
- Package dimension(mm): 436 x 346 x 198 (W x D x H)
- Without packing: 2.9kg
- With packing: 4.3kg

Environment

- Operating temperature: 0°C~40°C
- Storage temperature: -20°C~80°C
- Relative humidity: 10%~90%, non-condensing

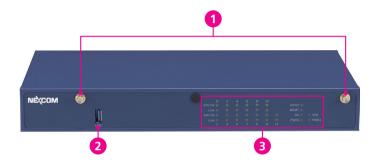
Certifications

- CE
- FCC Class B



Knowing Your DNA 1170

Front Panel



Rear Panel



1. Antenna Holes (DNA1170W Only)

Used for connecting antennas for Wi-Fi.

2. USB Ports

Used to connect USB 3.0/2.0 devices.

3. LED Indicators

Refer to LED Indicators section for more details.

4. Antenna Holes (DNA1170W Only)

Used for connecting antennas for 5G, LTE.

5. DC In 1 (19V)

Used to plug a DC power cord.

6. DC In 2 (19V)

Used to plug a DC power cord.

7. Power Button

Press to power-on or power-off the system.



Rear Panel



8. Reset Pin Hole

Press to restart the system.

9. Nano SIM Card Slot (Optional)

Used to plug a nano SIM cord.

10. RJ45 Console Port

Used to connect to a console device with an RJ45 port type.

11. RJ45 Management Port

Used to connect to a network for remote management and configuration.

12. SFP+ Ports

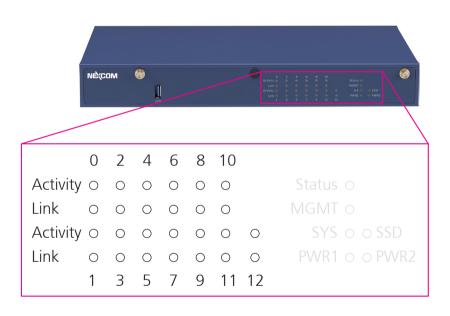
Used to connect to fiber optic networks, enabling long-distance networking or connections.

13. RJ45 LAN Ports

Used to connect to local area networks (LANs) or other networking devices at 1GbE speed.



LED Indicators



Port 0~7 Ethernet LEDs

LED	Behavior	Description
	Off	Inactive
Active/Traffic	Flashing Green	Active
	Flashing Green	Data transferring
llink —	Steady Green	1GbE network link.
	Steady Yellow -	100Mbps network link.

Port 8~11 Ethernet LEDs

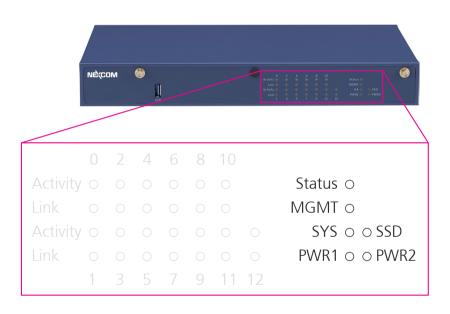
LED	Behavior	Description
	Off	Inactive
Active/Traffic	Flashing Green	Active
	Flashing Green	Data transferring
Link	Steady Green	10GbE network link.
LINK	Steady Yellow -	100Mbps network link.

Port 12 Ethernet LEDs

LED	Behavior	Description
	Off	Inactive
Active/Traffic	Flashing Green	Active
	Flashing Green	Data transferring
Link	Steady Green	2.5GbE network link.
Link	Steady Yellow -	100Mbps network link.



LED Indicators



Status LED

LED	Behavior	Description
	Off	Power off
Status	Steady Green	Power on
	Steady Orange	Standby

MGMT LED

LED	Behavior	Description
N 4	Off	Not connected
Magement	Steady Green	Connected

SYS LED

LED	Behavior	Description
System	Steady Green	Active

PWR1 and PWR2 LEDs

LED	Behavior	Description
PWR1	Steady Green	Power on
PWR2	Steady red	Power off

SSD LED

LED	Behavior	Description
CCD	Off	Off (default)
330	Flashing Green	Data transferring





CHAPTER 2: JUMPERS AND CONNECTORS

This chapter describes how to set the jumpers and connectors on the DNA 1170 series motherboard.

Before You Begin

- Ensure you have a stable, clean working environment. Dust and dirt can get into components and cause a malfunction. Use containers to keep small components separated.
- Adequate lighting and proper tools can prevent you from accidentally damaging the internal components. Most of the procedures that follow require only a few simple tools, including the following:
 - A Philips screwdriver
 - A flat-tipped screwdriver
 - A set of jewelers screwdrivers
 - A grounding strap
 - An anti-static pad
- Using your fingers can disconnect most of the connections. It is recommended that you do not use needle-nosed pliers to disconnect connections as these can damage the soft metal or plastic parts of the connectors.
- Before working on internal components, make sure that the power is off.
 Ground yourself before touching any internal components, by touching a metal object. Static electricity can damage many of the electronic components. Humid environments tend to have less static electricity than

dry environments. A grounding strap is warranted whenever danger of static electricity exists.

Precautions

Computer components and electronic circuit boards can be damaged by discharges of static electricity. Working on computers that are still connected to a power supply can be extremely dangerous.

Follow the guidelines below to avoid damage to your computer or yourself:

- Always disconnect the unit from the power outlet whenever you are working inside the case.
- If possible, wear a grounded wrist strap when you are working inside the
 computer case. Alternatively, discharge any static electricity by touching
 the bare metal chassis of the unit case, or the bare metal body of any
 other grounded appliance.
- Hold electronic circuit boards by the edges only. Do not touch the components on the board unless it is necessary to do so. Don't flex or stress the circuit board.
- Leave all components inside the static-proof packaging that they shipped with until they are ready for installation.
- Use correct screws and do not over tighten screws.



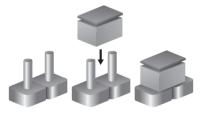


Jumper Settings

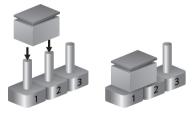
A jumper is the simplest kind of electric switch. It consists of two metal pins and a cap. When setting the jumpers, ensure that the jumper caps are placed on the correct pins. When the jumper cap is placed on both pins, the jumper is short. If you remove the jumper cap, or place the jumper cap on just one pin, the jumper is open.

Refer to the illustrations below for examples of what the 2-pin and 3-pin jumpers look like when they are short (on) and open (off).

Two-Pin Jumpers: Open (Left) and Short (Right)



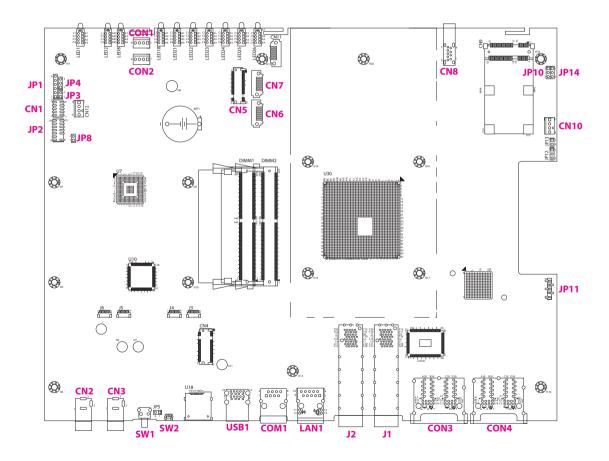
Three-Pin Jumpers: Pins 1 and 2 are Short





Locations of the Jumpers and Connectors

The following figure shows the mainboard used in the DNA 1170 series, and indicate the locations of the jumpers and connectors. Refer to this chapter for detailed pin settings and definitions of the connectors marked in pink on this figure.





Jumpers

RTC Clear

Connector type: 1x3 3-pin header

Connector location: JP10



Pin	Definition
1	NC
2	RST_SRTCRST_N
3	GND

Pin	Function
1-2 On	Normal (default)
2-3 On	Clear RTC

CMOS Clear

Connector type: 1x3 3-pin header



Pin	Definition
1	U7_V20
2	GND
3	U7_U18

Pin	Function
1-2 On	Normal (default)
2-3 On	Clear CMOS



Connector Pin Definitions

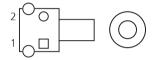
External I/O Interfaces DC In Jack

Connector location: CN2, CN3



Pin	Definition
1	DC_IN
2	GND
3	GND

Power Button



Pin	Definition
1	GND
2	PWRBTN#_IN
3	GND
4	GND



Reset Button

Connector location: SW2



2

3



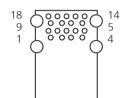
ACPI_BTN_IN# GND

GND

USB 3.0 Ports

Connector type: USB 3.0 port, Type A

Connector location: USB1



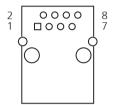


Pin	Definition
1,10	V5USB
2,11	USB2N0
3,12	USB2P0
5,14	USB3RN
6,15	USB3RP
8,17	USB3TN
9,18	USB3TP
4,13	USB_GND
7,16	טאום_סנט



RJ45 Console Port

Connector type: RJ45 Connector location: LAN1

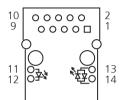




Pin	Definition
1	SP_RTS1
2	SP_DTR1
3	SP_TXD1
4	GND
5	SP_DCD1
6	SP_RXD1
7	SP_DSR1
8	SP_CTS1

RJ45 Management Port

Connector type: RJ45 Connector location: LAN1





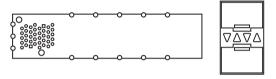
Pin	Definition
1,3,7,9	LAN_MDIP
2,4,8,10	LAN_MDIN0
5,6	GND
12	LED2_ACT_N
11	VCC3_LED
14	LED1_L2500_N
13	LED0_L1000_N

DNA 1170 Series User Manual



SFP+ Connectors

Connector type: SFP+cage Connector location: J1

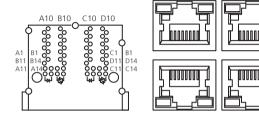


Pin	Definition	Pin	Definition
1	VEET	11	VEER
2	TXFAULT	12	RD-
3	TX_DISABLE	13	RD+
4	SDA	14	VEER
5	SCL	15	VCCR
6	MOD-ABS	16	VCCT
7	RS0	17	VEET
8	RX_LOS	18	TD+
9	RS1	19	TD-
10	VEER	20	VEET

RJ45 LAN Port

Connector type: RJ45

Connector location: COM3, COM4



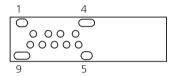
Pin	Definition
1	SP_RTS1
2	SP_DTR1
3	SP_TXD1
4	GND
5	SP_DCD1
6	SP_RXD1
7	SP_DSR1
8	SP_CTS1

12



USB 3.0 Port

Connector type: USB 3.0 port, Type A





Definition
V5USB
USB2N0
USB2P0
USB3RN
USB3RP
USB3TN
USB3TP
USB_GND



Internal Connectors CPLD_GPIO connector

Connector location: CN1



Pin	Definition	
1	P3V3_AUX	
2	GND	
3	CPLD_GPIN1	
4	CPLD_GPOUT1	
5	CPLD_GPIN2	
6	CPLD_GPOUT2	
7	CPLD_GPIN3	
8	CPLD_GPOUT3	
9	CPLD_GPIN4	
10	CPLD_GPOUT4	

M.2 Key M SATA SSD Connector

Connector location: CN5

Pin	Definition	Pin	Definition
1	SSD_DET_N	2	P3V3_SSD
3	GND	4	P3V3_SSD
5	NC	6	NC
7	NC	8	NC
9	GND	10	M.2_ACT_LED1
11	NC	12	P3V3_SSD
13	NC	14	P3V3_SSD
15	GND	16	P3V3_SSD
17	NC	18	P3V3_SSD
19	NC	20	NC
21	GND	22	NC
23	NC	24	NC

Continued on next page



Pin	Definition	Pin	Definition
25	NC	26	NC
27	GND	28	NC
29	NC	30	NC
31	NC	32	NC
33	GND	34	NC
35	NC	36	NC
37	NC	38	NGFF_DEVSLP
39	GND	40	NC
41	SATA2_RXP	42	NC
43	SATA2_RXN	44	NC
45	GND	46	NC
47	SATA2_TXN	48	NC
49	SATA2_TXP	50	SSD_RST_N

Pin	Definition	Pin	Definition
51	GND	52	SSD_CLKREQ#
53	CLK_100M_M2_SSD_N	54	MFG_CLK2
55	CLK_100M_M2_SSD_P	56	NC
57	GND	58	NC
59	Mechanical Key	60	Mechanical Key
61	Mechanical Key	62	Mechanical Key
63	Mechanical Key	64	Mechanical Key
65	Mechanical Key	66	Mechanical Key
67	Mechanical Key	68	CLK_32K_SUSCLK_SOC
69	GND	70	P3V3_SSD
71	GND	72	P3V3_SSD
73	GND	74	P3V3_SSD
75	GND		



SATA Connectors

Connector location: CN6, CN7







Pin	Definition	Pin	Definition
1	GND	2	SATA_TXP
3	SATA_TXN	4	GND
5	SATA_RXN	6	SATA_RXP
7	GND		

Pin	Definition
1	GND
2	P12V_FAN
3	FAN1_IN_CON
4	FAN1 PWM OUT



SATA Power Connector

Connector location: CON1, CON2



Pin	Definition
1	P12V_AUX
2	GND
3	GND
4	P5V

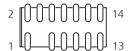
CPLD JTAG Header

Pin	Definition	
1	P3V3_AUX	
2	GND	
3	JTAG_PLD_TCK	
4	JTAG_PLD_TDO	
5	JTAG_PLD_TDI	
6	JTAG_PLD_TMS	



TPM Connector

Connector location: JP2



Pin	Definition
1,9,12,14	GND
5	LPC_AD2
7	LPC_AD1
11	LPC_SERIRQ
2	LPC_CLK_TPM
4	LPC_FRAME_N
6	RST_TPM_N
8	LPC_AD3
10	LPC_AD0

CPLD Remote Update Connector

Pin	Definition
1	JTAG_SEL
2	GND



SMB1 UART Connector

Connector location: JP4



Pin	Definition
1	U7_V20
2	GND
3	U7_U18

ME Recover Connector

Pin	Definition
1	JTAG_SEL
2	GND



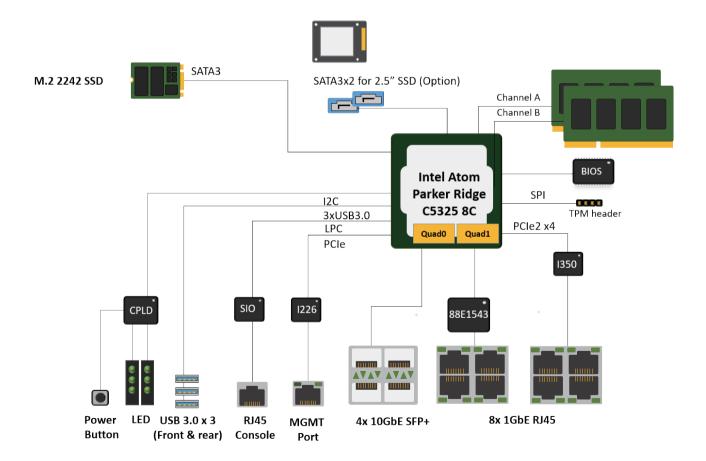
MCU Pin



Pin	Definition
1	MCU1_NMCLR
2	MCU_Vdd
3	GND
4	MCU1_PGED
5	MCU1_PGEC



Block Diagram



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CHAPTER 3: SYSTEM SETUP

Removing the Chassis Cover



Prior to removing the chassis cover, make sure the unit's power is off and disconnected from the power sources to prevent electric shock or system damage.

1. The screws around the cover are used to secure the cover to the chassis. Remove these screws and put them in a safe place for later use.





Note that the appearance of the chassis may vary, but the I/O ports and mechanics remain the same.

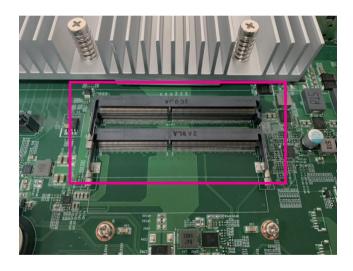
2. Gently slide the cover outwards, then lift up the cover to remove it.





Installing a SO-DIMM Memory Module

• With the cover removed, install a memory module in the SODIMM socket. Insert the module into the socket at an approximately 30-degree angle. Push the module down until the clips on both sides of the socket lock into position. The gold-plated connector on the edge of the module will almost completely disappear inside the socket.





1.

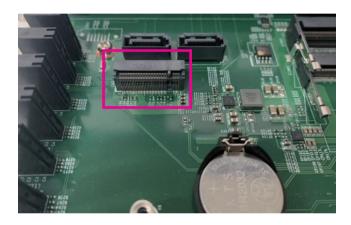


25



Installing a M.2 Storage Module

1. Locate the M.2 Key M slot on the motherboard.



2. Insert the M.2 module into the M.2 slot at a 45-degree angle until the gold-plated connector on the edge of the module completely disappears into the slot. Secure the M.2 module using the screw.





CHAPTER 4: BIOS SETUP

This chapter describes how to use the BIOS setup program for DNA 1170 series. The BIOS screens provided in this chapter are for reference only and may change if the BIOS is updated in the future.

To check for the latest updates and revisions, visit the NEXCOM Web site at www.nexcom.com.tw

About BIOS Setup

The BIOS (Basic Input and Output System) Setup program is a menu driven utility that enables you to make changes to the system configuration and tailor your system to suit your individual work needs. It is a ROM-based configuration utility that displays the system's configuration status and provides you with a tool to set system parameters.

These parameters are stored in non-volatile battery-backed-up CMOS RAM that saves this information even when the power is turned off. When the system is turned back on, the system is configured with the values found in CMOS.

With easy-to-use pull down menus, you can configure such items as:

- Hard drives, diskette drives, and peripherals
- Video display type and display options
- Password protection from unauthorized use
- Power management features

The settings made in the setup program affect how the computer performs. It is important, therefore, first to try to understand all the setup options, and second, to make settings appropriate for the way you use the computer.

When to Configure the BIOS

- This program should be executed under the following conditions:
- When changing the system configuration
- When a configuration error is detected by the system and you are prompted to make changes to the setup program
- When resetting the system clock
- When redefining the communication ports to prevent any conflicts
- When making changes to the Power Management configuration
- When changing the password or making other changes to the security setup

Normally, CMOS setup is needed when the system hardware is not consistent with the information contained in the CMOS RAM, whenever the CMOS RAM has lost power, or the system features need to be changed.



Default Configuration

Most of the configuration settings are either predefined according to the Load Optimal Defaults settings which are stored in the BIOS or are automatically detected and configured without requiring any actions. There are a few settings that you may need to change depending on your system configuration.

Entering Setup

When the system is powered on, the BIOS will enter the Power-On Self Test (POST) routines. These routines perform various diagnostic checks; if an error is encountered, the error will be reported in one of two different ways:

- If the error occurs before the display device is initialized, a series of beeps will be transmitted
- If the error occurs after the display device is initialized, the screen will display the error message.

Powering on the computer and immediately pressing lows you to enter Setup.

Legends

Key	Function	
← →	Moves the highlight left or right to select a menu.	
1	Moves the highlight up or down between sub-menu or fields.	
Esc	Exits the BIOS Setup Utility.	
+	Scrolls forward through the values or options of the highlighted field.	
-	Scrolls backward through the values or options of the highlighted field.	
Tab ! • ──→•	Selects a field.	
F1	Displays General Help.	
F2	Load previous values.	
F3	Load optimized default values.	
F4	Saves and exits the Setup program.	
Enter _J	Press <enter> to enter the highlighted sub-menu</enter>	





Scroll Bar

When a scroll bar appears to the right of the setup screen, it indicates that there are more available fields not shown on the screen. Use the up and down arrow keys to scroll through all the available fields.

Submenu

When " \blacktriangleright " appears on the left of a particular field, it indicates that a submenu which contains additional options are available for that field. To display the submenu, move the highlight to that field and press \blacksquare .

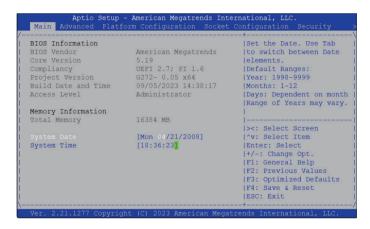


BIOS Setup Utility

Once you enter the AMI BIOS Setup Utility, the Main Menu will appear on the screen. The main menu allows you to select from several setup functions and one exit. Use arrow keys to select among the items and press to accept or enter the submenu.

Main

The Main menu is the first screen that you will see when you enter the BIOS Setup Utility.



System Date

The date format is <day>, <month>, <date>, <year>. Day displays a day, from Monday to Sunday. Month displays the month, from January to December. Date displays the date, from 1 to 31. Year displays the year, from 2005 to 2099.

System Time

The time format is <hour>, <minute>, <second>. The time is based on the 24-hour military-time clock. For example, 1 p.m. is 13:00:00. Hour displays hours from 00 to 23. Minute displays minutes from 00 to 59. Second displays seconds from 00 to 59.

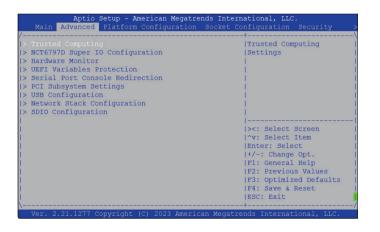


Advanced

The Advanced menu allows you to configure your system for basic operation. Some entries are defaults required by the system board, while others, if enabled, will improve the performance of your system or let you set some features according to your preference.

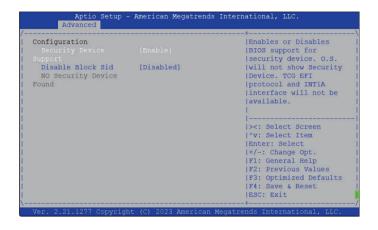


Setting incorrect field values may cause the system to malfunction.



Trusted Computing

This section is used to configure Trusted Platform Module (TPM) settings.



Security Device Support

Enables or disables BIOS support for security device. O.S will not show Security Device. TCG EFI protocol and INT1A interface will not be available.

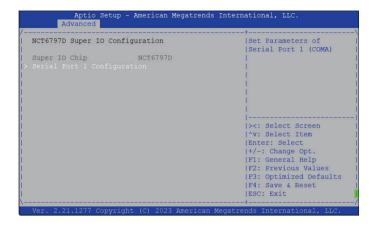
Disable Block Sid

Override to allow SID authentication in TCG storage device.



NCT6797D Super IO Configuration

This section is used to configure the serial port of the super IO.



Super IO Chip

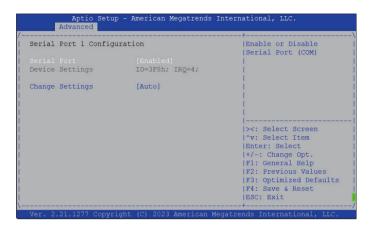
Display the Super I/O chip used on the board.

Serial Port 1 Configuration

Configure the IO/IRQ settings of serial port 1.

Serial Port 1 Configuration

This section is used to configure serial port 1.



Serial Port

Enable or disable the serial port.

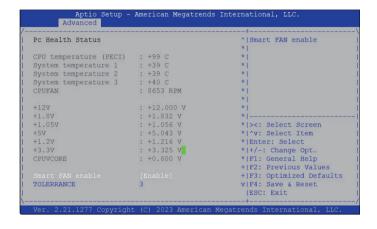
Change Settings

Select an optimal setting for the Super IO device.



Hardware Monitor

This section is used to monitor hardware status such as temperature, fan speed and voltages.



Smart FAN enable

Enable or disable the smart fan.

Tolerrance

Configure a tolerance for system fan target temperature.

UEFI Variables Protection



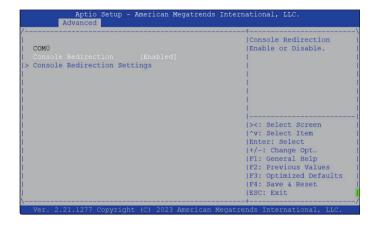
Password protection of Runtime Variables

Control the NVRAM runtime variable protection through system admin password.



Serial Port Console Redirection

This section is used to configure the serial port that will be used for console redirection.



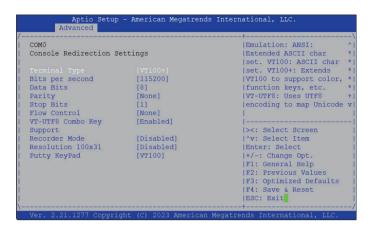
Console Redirection

Enable or disable the console redirection.

Console Redirection (Serial Port for Out-of-Band Management)

When the Console Redirection is enabled, the Console Redirection Settings will be available. Press <Enter> for additional configuration options.

Console Redirection Settings



Terminal Type

ANSI Extended ASCII character set.

VT100 ASCII character set.

VT100+ Extends VT100 to support color, function keys, etc.

VT-UTF8 Uses UTF8 encoding to map Unicode characters onto 1 or more

bytes.

Bits Per Second

Select the serial port transmission speed. The speed must match the other side. Long or noisy lines may require a lower speed.

Data Bits

40

The options are 7 and 8.







Parity

A parity bit can be sent with the data bits to detect some transmission errors.

Even Parity bit is 0 if the number of 1's in the data bits is even.

Odd Parity bit is 0 if number of 1's in the data bits is odd.

Stop Bits

Stop bits indicate the end of a serial data packet. (A start bit indicates the beginning). The standard setting is 1 stop bit. Communication with slow devices may require more than 1 stop bit.

Flow Control

Flow control can prevent data loss from buffer overflow. When sending data and the receiving buffers are full, a "stop" signal can be sent to stop the data flow.

VT-UTF8 Combo Key Support

Enable or disable VT-UTF8 combo key support.

Recorder Mode

When this field is enabled, only text will be sent. This is to capture the terminal data.

Resolution 100x31

Fnable or disable extended terminal resolution

Putty Keypad

Select the Putty keyboard emulation type.



PCI Subsystem Settings

This section is used to configure the PCI.



Above 4G Decoding

Enable or disable 64bit capable devices to be decoded in above 4G address space (only if the system supports 64 bit PCI decoding).

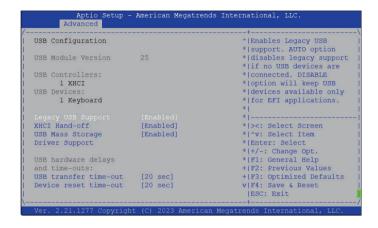
SR-IOV Support

Enable or disable SR-IOV support.



USB Configuration

This section is used to configure the USB.



Legacy USB Support

Enable Enables Legacy USB.

Auto Disables support for Legacy when no USB devices are connected.

Disable Keeps USB devices available only for EFI applications.

XHCI Hand-off

This is a workaround for OSs that does not support XHCI hand-off. The XHCI ownership change should be claimed by the XHCI driver.

USB Mass Storage Driver Support

Enable or disable USB mass storage driver support.

USB transfer time-out

The time-out value for control, bulk, and Interrupt transfers.

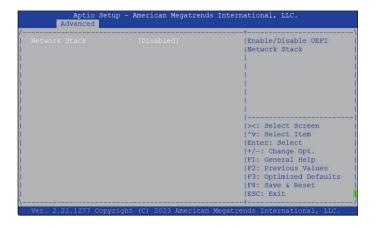
Device reset time-out

Select the USB mass storage device's start unit command timeout



Network Stack Configuration

This section is used to configure the network stack.

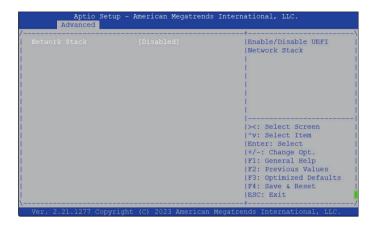


Network Stack

Enable or disable UEFI network stack.

SDIO Configuration

This section is used to configure the SDIO.



SDIO Access Mode

Auto option: Access SD device in DMA mode if controller supports it,

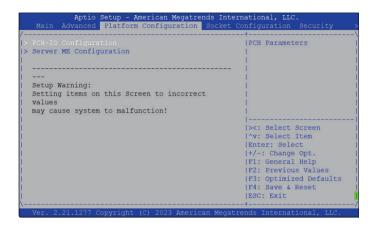
otherwise in PIO mode.

DMA option: Access SD device in DMA mode. PIO option: Access SD device in PIO mode.





Platform Configuration



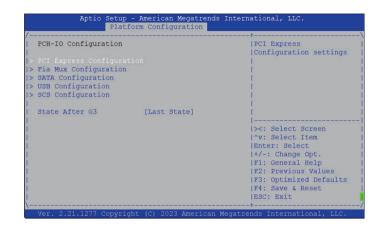
PCH-IO Configuration

Enter the PCH-IO Configuration submenu.

Server ME Configuration

Enter the Server ME Configuration submenu.

PCH-IO Configuration



PCI Express Configuration

Enter the PCI Express Configuration submenu.

Fia Mux Configuration

Enter the Fia Mux Configuration submenu.

SATA Configuration

Enter the SATA Configuration submenu.

USB Configuration

Enter the USB Configuration submenu.

SCS Configuration

Enter the SCS Configuration submenu.

State After G3

45

Configure the PCH state after G3.







PCI Express Configuration



PCI Express Root Port 1/3/4/9/10/11/12

Control the PCI Express Root Port.

ASPM

Enable or disable the ASPM.

L1 Substates

Configure the L1 Substates settings.

PCIe Speed

Configure the speed of the PCI Express port.

CT0

Configure the CTO for PCI Express.

Fia Mux Configuration

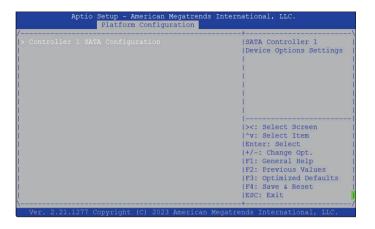


FIA Mux Configuration

By enabling this you override the platform configuration on FIA/WM.



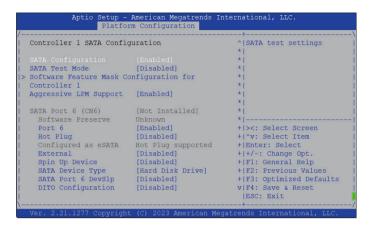
SATA Configuration



SATA Configuration

Enter the SATA Configuration submenu.

SATA Configuration > Controller 1 SATA Configuration



SATA Configuration

Enable or disable SATA configuration.

SATA Test Mode

Enable or disable SATA test mode.

Software Feature Mask Configuration for Controller 1

Enable or disable software feature mask configuration for controller 1.

Aggressive LPM Support

Enable or disable aggressive LPM support.

Port 6

Enable or disable SATA port 6.







Hot Plug

Enable or disable hot plugging feature on SATA port 6.

External

Enable or disable the feature of External.

Spin Up Device

Enable or disable staggered spin up on devices connected to SATA port 6.

SATA Device Type

Identiy what type of SATA device is connected.

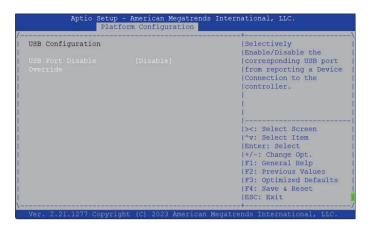
SATA Port 6 DevSlp

Enable or disable SATA Port 1/3 DevSlp. Before enabling DevSlp, board rework is needed.

DITO Configuration

Enable or disable DITO configuration.

USB Configuration



USB Port Disable Override

Selectively enable or disable the corresponding USB port from reporting a device connection to the controller.



SCS Configuration



eMMC 5.1 Controller

Enable or disable SCS eMMC 5.1 controller.

eMMC 5.1 HS400 Mode

Enable or disable SCS eMMC 5.1 HS400 mode.

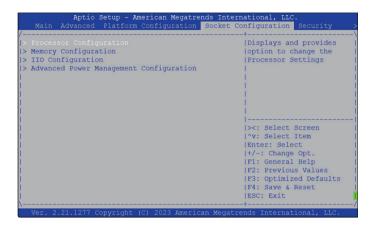
General ME Configuration

Display information of the firmware installed in the system.

General ME Configuration	n	T T
Oper. Firmware Version	12:5.0.3.216	i i
Backup Firmware Version	N/A	
Recovery Firmware Version	12:5.0.3.216	
ME Firmware Status #1	0x00000255	i i
ME Firmware Status #2	0x8A116026	i i
Current State	Operational	i i
Error Code	No Error	j
Recovery Cause	N/A	><: Select Screen
		^v: Select Item
		Enter: Select
		+/-: Change Opt.
		F1: General Help
		F2: Previous Values
		F3: Optimized Defaults
		F4: Save & Reset
		IESC: Exit



Socket Configuration



Processor Configuration

Enter the Processor Configuration submenu.

Memory Configuration

Enter the Memory Configuration submenu.

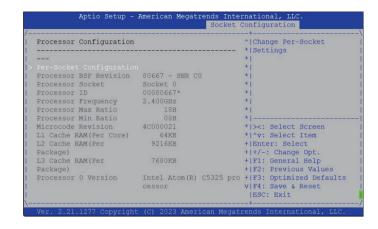
IIO Configuration

Enter the IIO Configuration submenu.

Advanced Power Management Configuration

Enter the Advanced Power Management Configuration submenu.

Processor Configuration

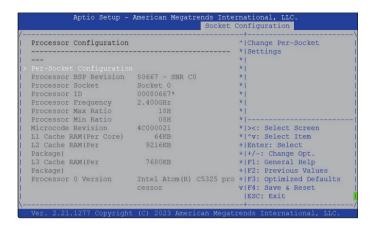


Pre-Socket Configuration

Enter the Pre-Socket Configuration submenu.



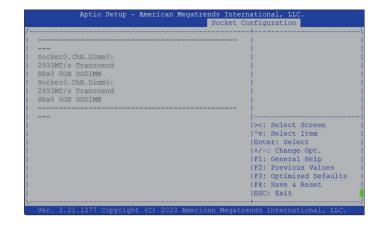
Pre-Socket Configuration



Pre-Socket Configuration

Change pre-socket settings.

Memory Configuration

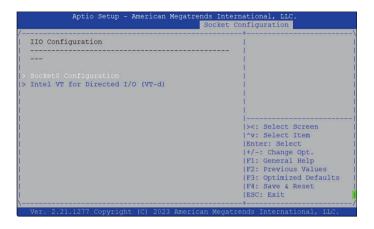


Memory Topology

Display memory topology with DIMM population information.



IIO Configuration



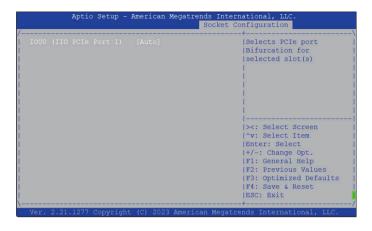
Socket0 Configuration

Enter the Socket0 Configuration submenu.

Intel VT for Directed I/O (VT-d)

Enter the Intel VT for Directed I/O (VT-d) submenu.

Socket0 Configuration



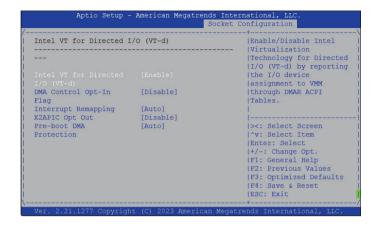
IOU0 (IIO PCIe Port 1) [Auto]

Select PCIe port bifurcation for selected slot(s).

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Intel VT for Directed I/O (VT-d)



Intel VT for Directed I/O (VT-d)

Enable or disable Intel Virtualization Technology for Directed I/O (VT-d) by reporting the I/O device assignment to VMM through DMAR ACPI Tables.

DMA Control Opt-In Flag

Enable or disable the DMA Control Opt-In Flag.

Interrupt Remapping

Configure the Interrupt Remapping.

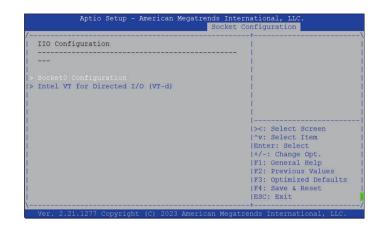
X2APIC Opt-Out

Enable or disable the X2APIC mode.

Pre-boot DMA Protection

Enable or disable the Pre-boot DMA Protection

Advanced Power Management Configuration



CPU P State Control

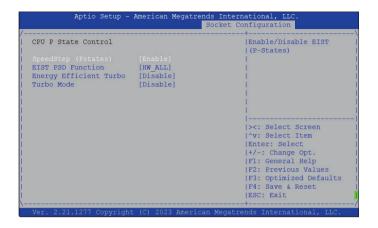
Enter the CPU P State Control submenu.

CPU C State Control

Enter the CPU C State Control submenu.



CPU P State Control



SpeedStep (PStates)

Enable or disable EIST (P-State).

EIST PSD Function

Select a preferred option for EIST PSD.

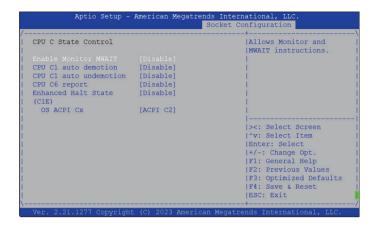
Energy Efficient Turbo

Enable or disable the Energy Efficient Turbo.

Turbo Mode

Enable or disable the turbo mode.

CPU C State Control



Enable Monitor MWAIT

Enable or disable monitoring and MWAIT instructions.

CPU C1 auto demotion

Enable or disable CPU C1 auto demotion.

CPU C1 auto undemotion

Enable or disable CPU C1 auto undemotion.

CPU C6 report

Enable or disable C6 report to the operating system.

Enhanced Halt State (C1E)

Enable or disable Enhanced Halt State (C1E) for lower power consumption.

OS ACPI Cx

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Enable or disable C3 report or C6 report to OS ACPI C2 or ACPI C3.





Security

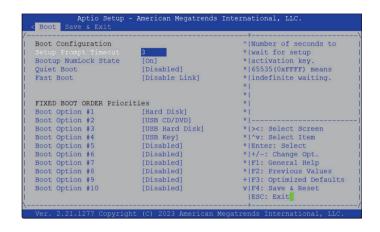


Administrator Password

Select to reconfigure the administrator's password.



Boot



Setup Prompt Timeout

Select the number of seconds to wait for the setup activation key. 65535(0xFFFF) denotes indefinite waiting.

Bootup NumLock State

This allows you to determine the default state of the numeric keypad. By default, the system boots up with NumLock on wherein the function of the numeric keypad is the number keys. When set to Off, the function of the numeric keypad is the arrow keys.

Quiet Boot

Enabled Display OEM logo instead of the POST messages.

Disabled Display normal POST messages.

Fast

Fast Boot

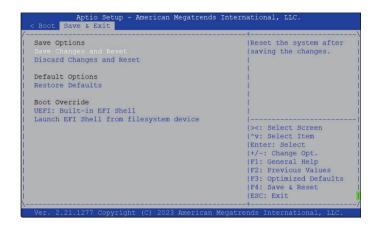
Enable or disable boot with initialization of a minimal set of devices required to launch active boot option. Has no effect for BBS boot options

Boot Option #1 to Boot Option #10

Adjust the boot sequence of the system. Boot Option #1 is the first boot device that the system will boot from, next will be Boot Option #2 and so forth.



Save & Exit



Save Changes and Reset

To save the changes and reset, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Discard Changes and Reset

To exit the Setup utility and reset without saving the changes, select this field then press <Enter>. You may be prompted to confirm again before exiting.

Restore Defaults

To restore the BIOS to default settings, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Launch EFI Shell from filesystem device

To launch EFI shell from a filesystem device, select this field and press <Enter>.